

U.S. Patent Application Serial No. 10/028,359
Response filed March 10, 2005
Reply to OA dated November 10, 2004

AMENDMENTS TO THE ABSTRACT:

Delete the current Abstract and replace therewith the replacement Abstract of the Disclosure on a separate sheet attached hereto.

The corrections to the Abstract are indicated below:

~~The present invention provides an~~ An electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, and a member for rotating the work about its center axis and supplying a plating electric current to the work. ~~The present invention also provides an electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, a member for rotating the work about its center axis, and a~~ Alternatively, a separate member for supplying ~~a~~ may supply the plating electric current to the work. ~~Further, the present invention provides an electroplating device including an anode inserted through and disposed in a hole provided in a work and communicating with the outside, and a means for allowing a~~ A plating solution in the hole in the work may be allowed to flow. Thus, a uniform plated film can be formed on both of the outer and inner surfaces of the work having the hole communicating with the outside such as a ring-shaped work, of which a ring-shaped bonded magnet is representative, by using the electroplating device.